

Product Texts

Zytel® HTNFR51G35L BK337 is a 35% Glass Reinforced, Flame Retardant, PPA, High Performance Polyamide

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.1 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.5 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	14000 / 14500	MPa	ISO 527
^[C] Stress at break	174 / 162	MPa	ISO 527
^[C] Strain at break	1.6 / 1.3	%	ISO 527
^[C] Charpy impact strength, +23°C	35 / 30	kJ/m ²	ISO 179/1eU
^[C] Charpy impact strength, -30°C	25 / 25	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	12 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	300 / *	°C	ISO 11357-1/-3
^[C] Glass transition temperature, 10°C/min	135 / *	°C	ISO 11357-1/-2
^[C] Temp. of deflection under load, 1.80 MPa	262 / *	°C	ISO 75-1/-2
^[C] Burning Behav. at 1.5 mm nom. thickn.	V-0 / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Burning Behav. at thickness h	V-0 / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Oxygen index	41 / *	%	ISO 4589-1/-2

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Relative permittivity, 100Hz	3.9 / -	-	IEC 62631-2-1
^[C] Relative permittivity, 1MHz	3.6 / -	-	IEC 62631-2-1
^[C] Dissipation factor, 100Hz	80 / -	E-4	IEC 62631-2-1
^[C] Dissipation factor, 1MHz	150 / -	E-4	IEC 62631-2-1
^[C] Volume resistivity	>1E13 / -	Ohm*m	IEC 62631-3-1
^[C] Surface resistivity	* / >1E15	Ohm	IEC 62631-3-2

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1670 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Regional Availability

North America, Europe, Asia Pacific, South and Central America

Special Characteristics

Flame retardant

Other text information

Injection molding

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

When lower mold temperatures are used, the initial warpage and shrinkage may be lower, but the surface appearance and chemical resistance may be reduced, and the dimensional change may be greater when parts are subsequently heated.